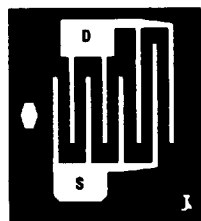


PRODUCT CATALOG

P-CHANNEL JUNCTION FET

CHIP NUMBER

FP5.3



.020"
(0.508mm)

.015"
(0.381mm)

Die Size: .15 x .20 (mils)
0.381 x 0.508(mm)
3 x 4 (mils)
Pad Size: 0.076 x 0.102(mm)
GATE-SUBSTRATE

CONTACT METALLIZATION

Top Contact: > 12,000
Å Aluminum

Backside Contact: 3,000 Å Gold

ASSEMBLY RECOMMENDATIONS

It is advisable that:

- the die be eutectically mounted with gold silicon preform 98/2%.
- 1 mil (0.0254mm) aluminum wire be ultrasonically attached to the top contact.

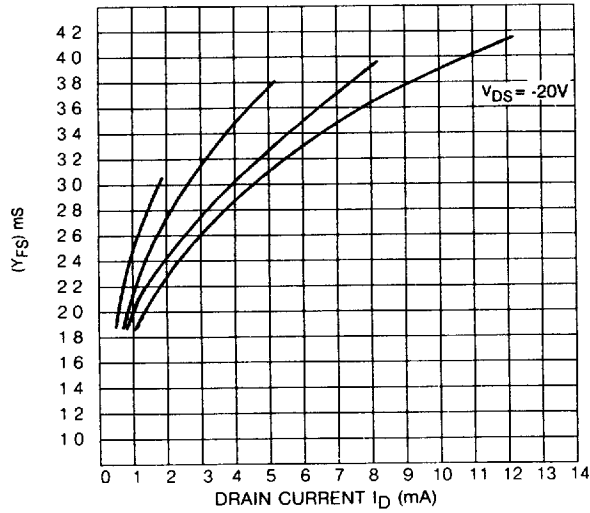
TYPICAL ELECTRICAL CHARACTERISTICS

PARAMETER	MIN.	TYP	MAX.	UNIT	TEST CONDITIONS
B_{VGSS}	30	40	50	V	$V_{DS} = -0, I_G = 1\mu A$
I_{DSS}	0.5	8.0	20	mA	$V_{DS} = -20V, V_{GS} = 0$
g_{fs}		4000		μmho	$V_{DS} = -20V, V_{GS} = 0$
I_{GSS}		30	200	pA	$V_{GS} = -20V, V_{DS} = 0$
r_{DS}		300		Ω	$V_{DS} = 100mV, V_{GS} = 0$
$V_{GS(off)}$	1.0	2.5	8.0	V	$V_{DS} = -20V, I_D = 1nA$
C_{rss}		1.8	2.5	pF	$V_{DS} = -20V, V_{GS} = 0, f = 1MHz$
C_{iss}		7.0	9.0	pF	$V_{DS} = -20V, V_{GS} = 0, f = 1MHz$

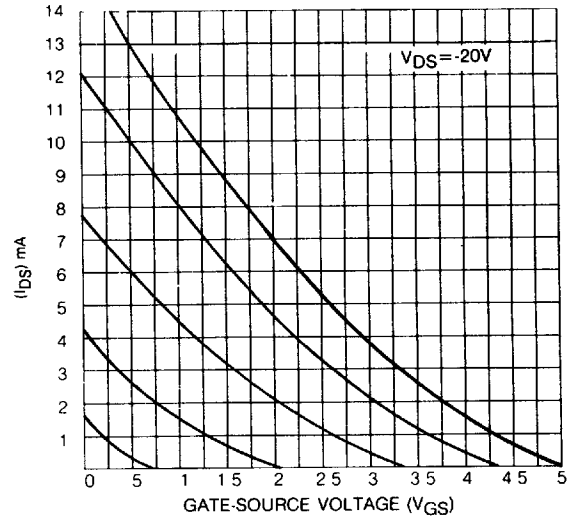
TYPICAL DEVICE TYPES: UC400, UC410, UC420, 2N2607, 2N2608, 2N2609, 2N2842, 2N2844

CHIP TYPE FP5.3

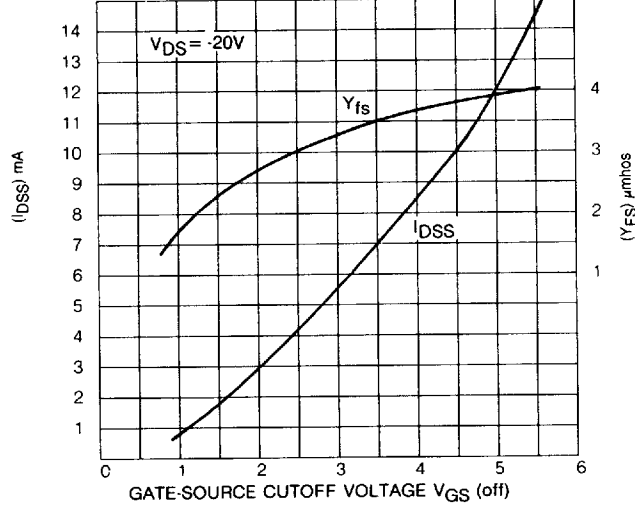
FORWARD TRANSADMITTANCE
VS OPERATING DRAIN CURRENT



TRANSFER CHARACTERISTICS



FORWARD TRANSADMITTANCE
VS GATE-SOURCE CUTOFF VOLTAGE



OUTPUT TRANSFER CHARACTERISTICS

